



## Material Declaration Data Sheet

Product: **Server System SR6850HW4M**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **NO**

Date: June 16, 2006

### Restriction on Hazardous Substances (RoHS) Compliance

#### RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

#### RoHS Declaration

- 1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4. Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8. Lead used in compliant pin connector systems.
- 9. Lead as a coating material for the thermal conduction module c-ring.
- 10. Lead in optical and filter glass.
- 11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13. Cadmium in optical and filter glass.
- 14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (\*) amending Directive 76/769/EEC (\*\*) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15. Lead in bronze bearing shells and brushes.
- 16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

# Product Code Information



Product Code	Description	*RoHS Exemption #
AHW6UPBEZEL	PEDESTAL BEZEL (BLACK) FOR 6U	None
AHW6UPEDKIT	PROD CODE, 6U CHASSIS PED CONVERSION KIT	,2
AHW6UPWR	PROD CODE, PS MODULE (15AMP)	,6
AHW6UPWR23	PROD CODE, PS MODULE (15AMP)	,6
AHW6UPWRFAN	PROD CODE, ACTIVE PS FAN BLANK 6U	,6
AHW6URBEZEL	RACK BEZEL (BLACK) FOR 6U RACK	None
AHWEXTSCSI	INTERNAL CABLE FOR EXTERNAL SCSI PORT	None
AHWIMMADV2	PROD CODE, IMM, ADV, HW, GOLD	,6
AHWIMMPRO2	PROD CODE, IMM, PRO, GOLD	,6
AHWINTSCSI	INTERNAL SCSI CBL (TO 5.25" BAY )	None
AHWPCISCSI	PROD CODE, PCI SCSI CABLE, 800T	,6
AHWPROCBLANK	INTEL CEK PROCESSOR HEATSINK	,2
AHWPROCHS	INTEL CEK PROCESSOR HEATSINK	,6
AHWVRMCM	DUAL-OUTPUT PROCESSOR VRM	None
AHWVRMPM	10.2 PROCESSOR VRM PAXVILLE MP	None
AXXBCPMOD2	PROD CODE, BUTTON CONTROL MODULE	,6
AXXCMA3U7U	RACK CABLE MANAGEMENT ARM. 3U-7U CHASSI	None
AXXLCPMOD2	PROD CODE, LCD MOD, RACK	None
AXXRAIL3U7U	RACK RAILS FOR 3U-7U CHASSIS. J-HOOK DE	None
AXXRAKU42E	INTELR RAID ACTIVATION KEY	,6
BHW4DIMMM	PROD CODE, MEMORY BOARD	,6
BHWBASEM	PROD CODE, BASEBOARD - IO PER, H800T	,6
FHW6UCPSCSI	CNTL PNL TO SCSI BP FOR SR6850HW4. (50P)	None
FHW6UFAN	PROD CODE, SYSTEM FAN, 6U	,6
FHW6UFPSATA	FRNT PNL AND SATA BUNDLE FOR SR6850HW4	,6
FHW6UFPSCSI	FRNT PNL TO SCSI BP FOR SR6850HW4. (34P)	,6
FHW6UFRTPNL	PROD CODE, FRONT IO PANEL BOARD, 6U	,6
FHW6UINTSCSIA	PROD CODE, INT SCSI CABLE, BP, A, 6U	,6
FHW6UINTSCSIB	PROD CODE, INT SCSI CABLE, BP, B, 6U	,6
FHW6UPBAYSCSI	PWR, PBAY TO SCSI BP FOR SR6850HW4. (4P)	,6
FHW6UPCILATCH	PCI CARD HOLD DOWN LATCHES (8)	,6
FHW6UPDB	PROD CODE, POWER DISTRIBUTION BOARD, 6U	,6
FHW6UPRODUCT	PROCESSOR AIR DUCT FOR SR6850HW4.	,6
FHW6USATASCSI	SATA TO SCSI BP FOR SR6850HW4. (PWR)	,6
FHW6USCSIBP	PROD CODE, SCSI BACKPLANE, 6U	,6
FHWINTRU	INTRUSION SWITCH SR4850HW4 SR6850HW4	,6
FHWPCIDIVIDER	PCI DIVIDERS	,6
FHWSATAIDE	SATA TO IDE BRIDGE	,6
AXXRSBBU3	PROD CODE, AXXRSBBU3, BATTERY	None

\* RoHS Exemption # corresponds with exemption #'s found on page 1.

